FEB 2 7 2004 FEB 2

In Re Patent Application of:

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

	Harry Q. Pon	Art Unit: 2826
Applic	cation No.: 09/822,944 )	Art Unit: 2620
Filed:	March 30, 2001	
For:	INSULATED BOND WIRE ASSEMBLY PROCESS TECHNOLOGY FOR INTEGRATED CIRCUITS )	
P.O. B	nissioner for Patents  Box 1450  andria, VA 22313-1450	
Піоли	AMENDMENT	
Sir:		
In response to the Office Action mailed November 20, 2003, please amend the above-		
identified application as follows.		
Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.		
Remarks/Arguments begin on page 6 of this paper.		
I hereby state that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on		
F	February 20, 2004  Date of Deposit	
<u>Debora</u>	ah A. McGovern	·

February 20, 2004 Date